

# Abhishek Patnaik

## List of Publications by Year in descending order

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14  
papers

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citations

1684188

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docs citations

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times ranked

88  
citing authors

#	ARTICLE	IF	CITATIONS
1	Radiated EMI Estimation From DC-DC Converters With Attached Cables Based on Terminal Equivalent Circuit Modeling. IEEE Transactions on Electromagnetic Compatibility, 2018, 60, 1769-1776.	2.2	39
2	An On-Chip Detector of Transient Stress Events. IEEE Transactions on Electromagnetic Compatibility, 2018, 60, 1053-1060.	2.2	14
3	Characterizing ESD stress currents in human wearable devices. , 2017, , .		10
4	Terminal Modeling of DC-DC Converters With Stochastic Behavior. IEEE Transactions on Electromagnetic Compatibility, 2018, 60, 2011-2018.	2.2	10
5	EMI Prediction of Multiple Radiators. IEEE Transactions on Electromagnetic Compatibility, 2020, 62, 415-424.	2.2	10
6	Measurement Techniques to Identify Soft Failure Sensitivity to ESD. IEEE Transactions on Electromagnetic Compatibility, 2020, 62, 1007-1016.	2.2	8
7	Source isolation measurements in a multi-source coupled system. , 2017, , .		6
8	Common mode current prediction from a power converter with attached cables based on a terminal equivalent circuit model. , 2016, , .		4
9	A Transient Event Sensor for Efficient System-Level ESD Testing. IEEE Transactions on Electromagnetic Compatibility, 2018, 60, 1231-1239.	2.2	4
10	Systematic Evaluation of Soft Failures in System-Level ESD Transient Events. IEEE Transactions on Electromagnetic Compatibility, 2018, 60, 1263-1269.	2.2	3
11	Growth of Radiated Emission in Multi-Modular Systems. IEEE Transactions on Electromagnetic Compatibility, 2020, 62, 612-616.	2.2	3
12	Measurement-Based Validation of Integrated Circuit Transient Electromagnetic Event Sensors. IEEE Transactions on Electromagnetic Compatibility, 2020, 62, 1555-1562.	2.2	2
13	EMI Analysis of DVI Link Connectors. IEEE Transactions on Electromagnetic Compatibility, 2018, 60, 149-156.	2.2	1
14	Experimental Validation of an Integrated Circuit Transient Electromagnetic Event Sensor. , 2019, , .		1